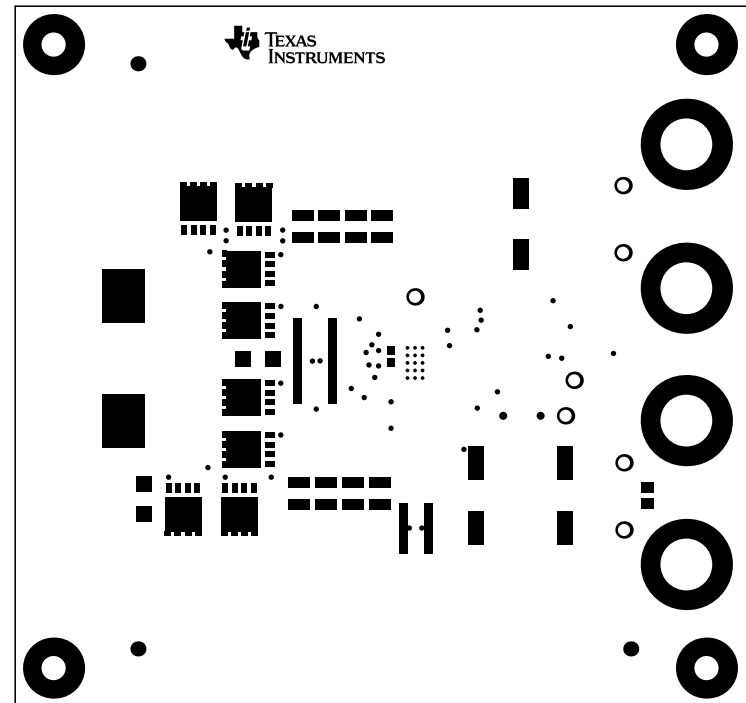
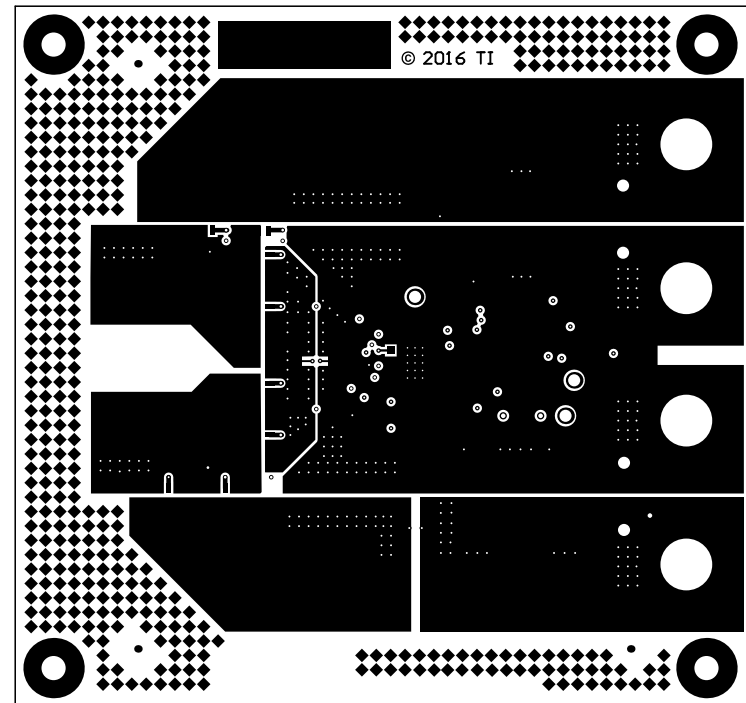


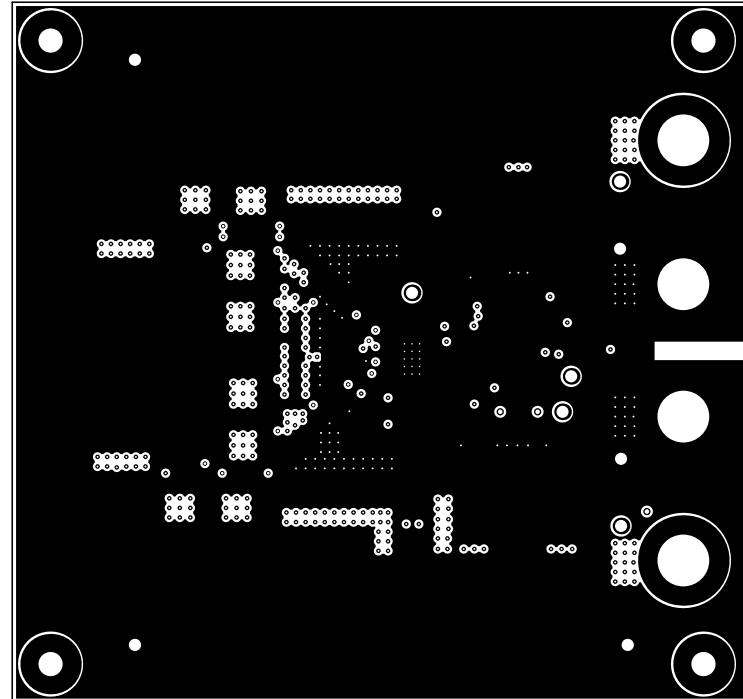
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/28/2017 2:30:20 PM	TEXAS INSTRUMENTS	



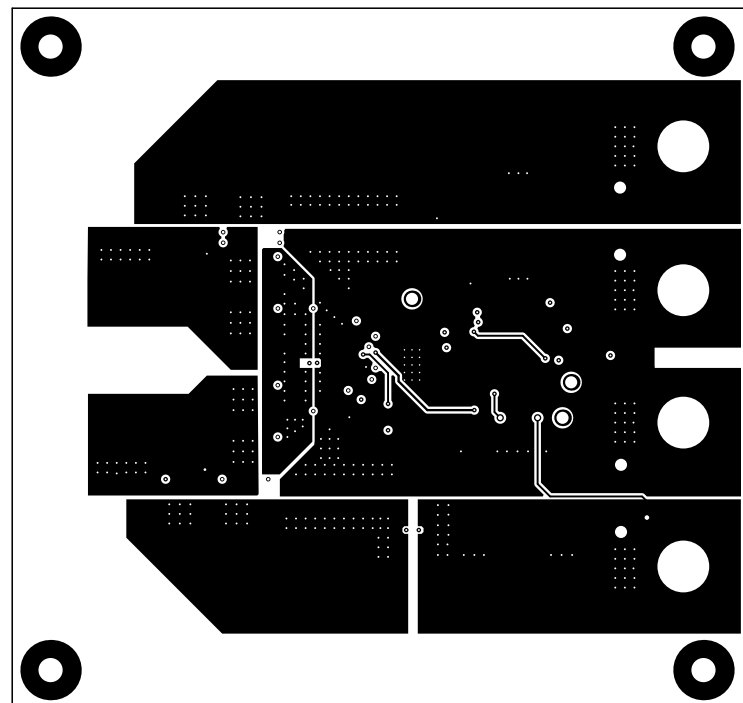
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/28/2017 2:30:20 PM	TEXAS INSTRUMENTS	



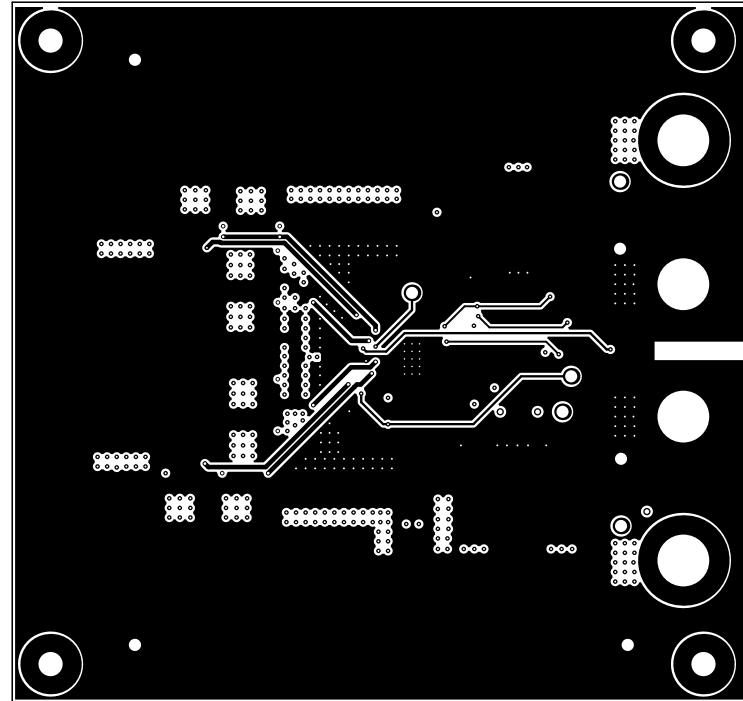
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/28/2017 2:30:21 PM	TEXAS INSTRUMENTS	



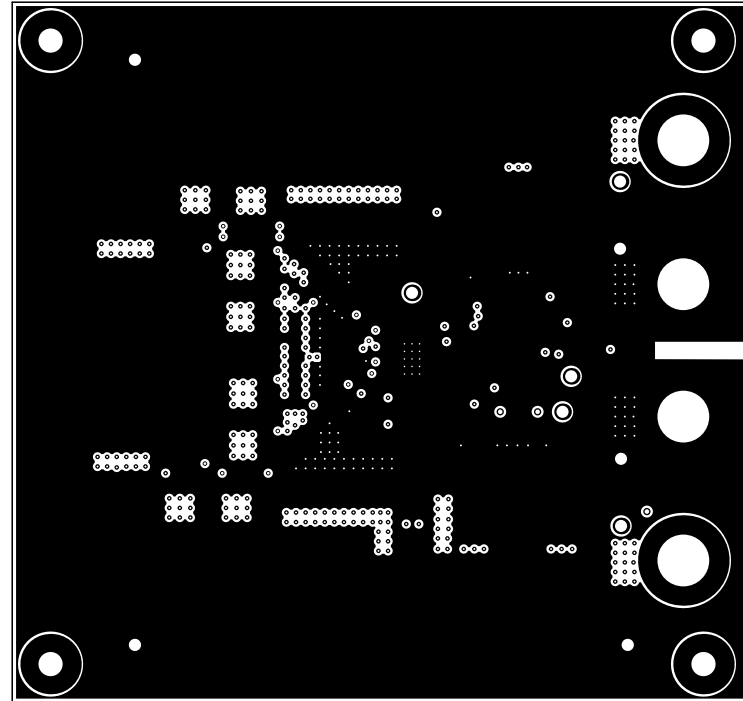
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Signal Layer 1	GENERATED : 11/28/2017 2:30:22 PM	TEXAS INSTRUMENTS	



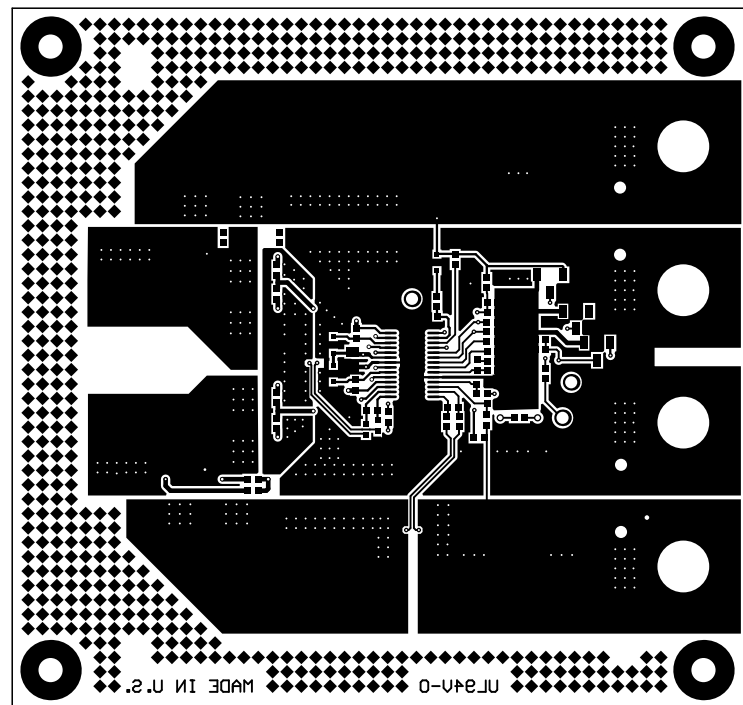
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Signal Layer 2	GENERATED : 11/28/2017 2:30:22 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = MidLayer3			
PLOT NAME = Signal Layer 3	GENERATED : 11/28/2017 2:30:23 PM	TEXAS INSTRUMENTS	

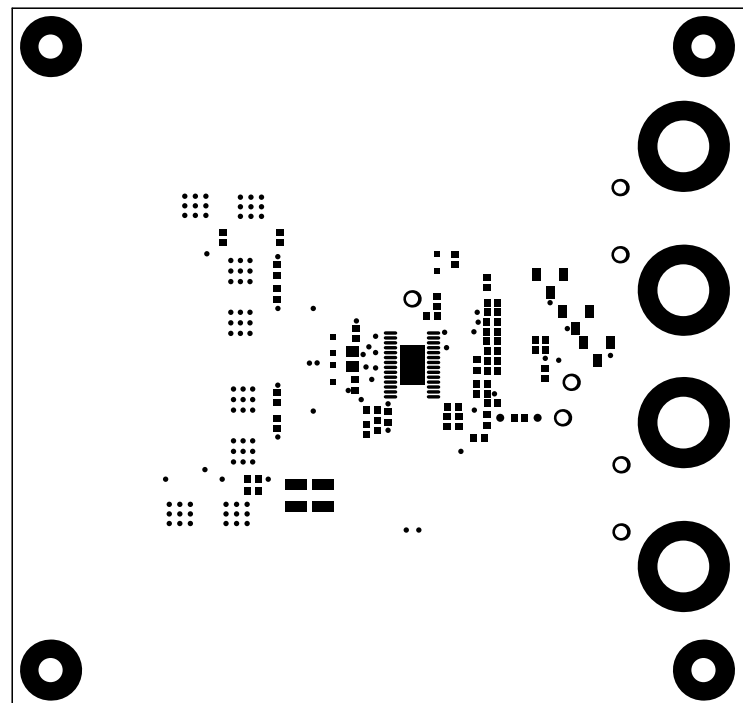


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = MidLayer 4			
PLOT NAME = Signal Layer 4	GENERATED : 11/28/2017 2:30:24 PM	TEXAS INSTRUMENTS	

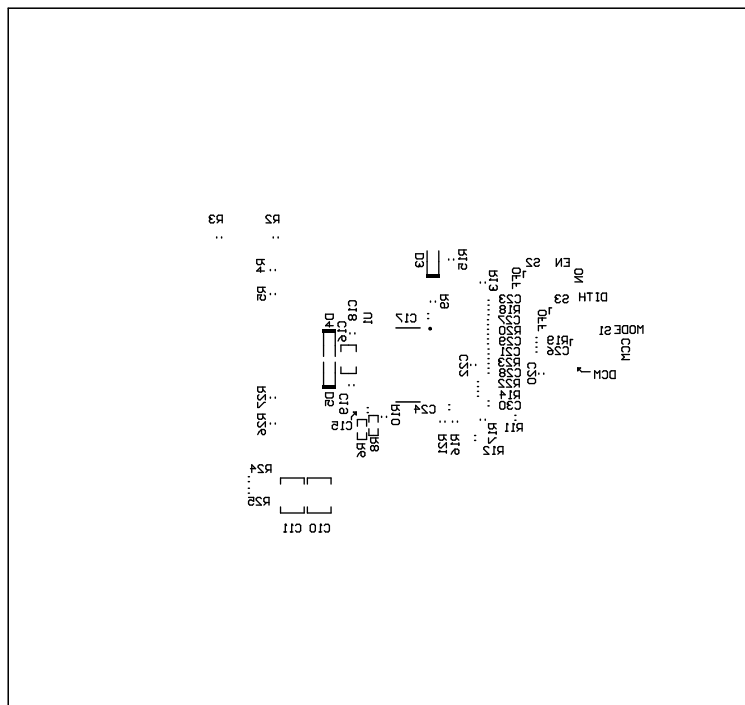


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/28/2017 2:30:24 PM	TEXAS INSTRUMENTS	

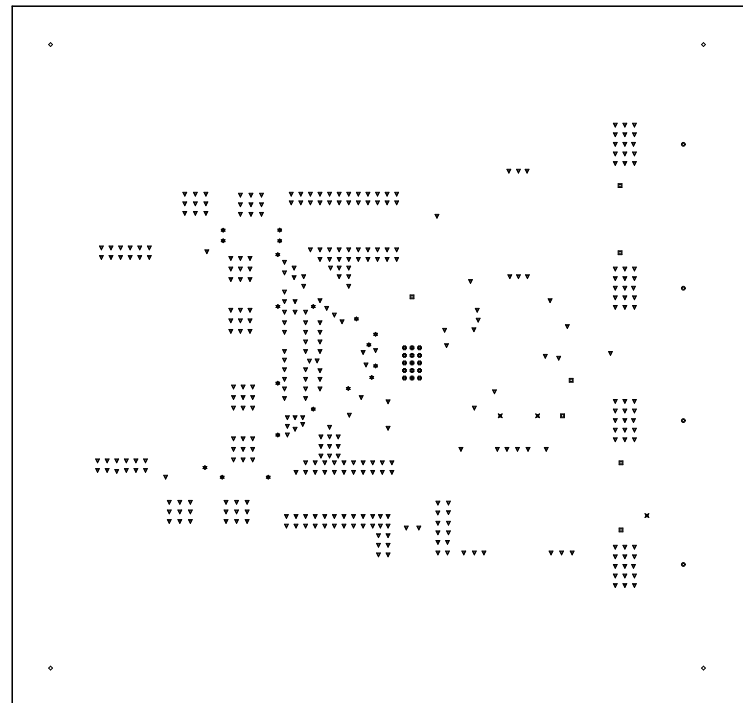




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/28/2017 2:30:25 PM	TEXAS INSTRUMENTS	

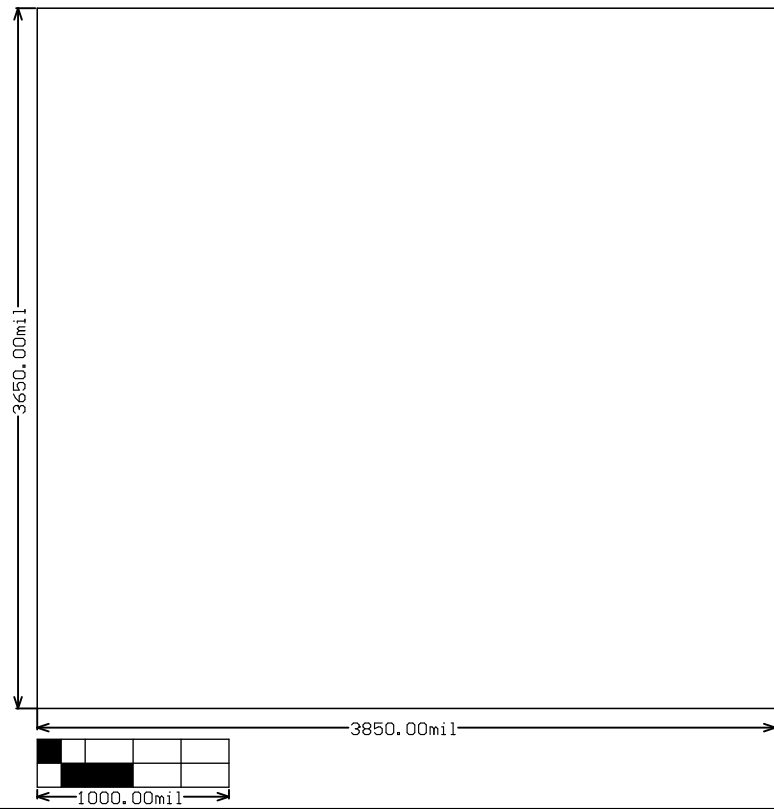


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/28/2017 2:30:26 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
✕	3	24.00mil (0.610mm)	PTH	Round
◇	4	125.98mil (3.200mm)	PTH	Round
◎	4	270.00mil (6.858mm)	PTH	Round
□	7	63.00mil (1.600mm)	PTH	Round
⊗	15	7.87mil (0.200mm)	PTH	Round
★	19	14.00mil (0.356mm)	PTH	Round
▽	369	10.00mil (0.254mm)	PTH	Round
	421	Total		

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In Version Control
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/28/2017 2:30:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/28/2017 2:30:28 PM	TEXAS INSTRUMENTS	

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